

China Technology

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Implications of the US's updated chip restrictions to global/domestic SPE and GPU companies

The US Department of Commerce announced a new set of restrictions on 17 Oct ([link](#)) that strengthens 1) export controls on advanced chips with new "parameters" and expansion to 40 more countries, 2) export controls of chip manufacturing equipment to 21 more countries, and 3) addition of 13 Chinese entities onto the US Entity List. We believe new rules are largely in-line with expectations and news media on 3 Oct ([link](#)). Overall, this is an update to US restrictions released in Oct 2022 ([our note](#)), which we believe aims to limit the access to advanced chips/tools, in line with new Dutch and Japanese rules ([our note](#)), and close loopholes in export restrictions on tailored-made AI chips (e.g. A800, H800). In our view, the US's recent export controls and CHIPS Act will accelerate the localization of semi equipment/foundries in China given supply chain security concerns and geopolitical tensions. Despite recent macro weakness and short-term cyclical downturn, we believe semi localization remains the structural growth driver in the long run.

- **What are the new rules? 1) "Parameter" changes for advanced chips:** the existing parameter "interconnect bandwidth" for advanced chips is replaced by a new parameter "performance density threshold" to prevent workarounds like chiplets technology. **2) Expansion of advanced chip/tool export controls to 40/21 more countries:** this rule aims to restrict chip exports to firms with parentco headquartered in China. **3) 13 Chinese firms added to the US Entity List:** the list includes two GPU companies, Biren Tech and Moore Threads, which aims to restrict the development of domestic AI chips, on top of access limits to Nvidia/AMD AI chips.
- **Diverse impacts on global/domestic GPU companies.** While Nvidia/AMD/Intel's advanced chip exports to China will be impacted in the near term, the updated rules do not restrict access to US or allied cloud computing services through IaaS in the meantime. For domestic names, two Chinese GPU companies (Biren Tech/壁仞科技, Moore Threads/摩尔线程) are added onto the Entity List, and their major products are general-purpose GPUs designed for servers in the China market. We believe this restriction will impact their production plan and customer base expansion overseas. We expect they will move from overseas foundries (TSMC/Samsung) to domestic advanced process foundries (SMIC) for foundry services, similar to Cambricon/寒武纪 and Loongson/龙芯.
- **Limited impact on global SPE; positive to domestic SPE/foundry.** ASML stated the new rules would apply to "a limited number of fabs in China" involved in advanced chips manufacturing, and did not expect a material impact on its financial outlook for 2023 and for longer-term scenarios. For domestic names, we expect Naura and AMEC to continue to benefit from accelerated SPE localization and domestic IDM/foundry expansion.

Valuation Table

Name	Ticker	Mkt Cap (US\$ mn)	Price (LC)	P/E (x)		P/B (x)		ROE
				FY23E	FY24E	FY23E	FY23E	FY23E
SMIC	981 HK	30,361	20.55	21.7	21.4	1.0		4.7
Hua Hong Semi	1347 HK	5,922	19.68	12.4	13.9	0.8		7.1
Naura	002371 CH	17,867	246.67	36.7	28.2	5.7		15.9
AMEC	688012 CH	14,044	166.20	63.9	55.7	6.0		9.7
Cambricon	688256 CH	6,575	115.47	-	-	9.9	(14.0)	

Source: Company data, CMBIGM estimates

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2. Implications of US's new chip export restrictions to China - 10 Oct 2022 ([link](#))
3. U.S. may broaden AI chips export restrictions - 14 Sep 2022 ([link](#))

Figure 1: US BIS to strengthen restrictions on advanced computing semiconductors, semiconductor manufacturing equipment, and supercomputing items to countries of concern



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<https://bis.doc.gov>

BUREAU OF INDUSTRY AND SECURITY

Office of Congressional and Public Affairs

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Commerce Strengthens Restrictions on Advanced Computing Semiconductors, Semiconductor Manufacturing Equipment, and Supercomputing Items to Countries of Concern

Updates to Modify and Reinforce Restrictions Initially Released on October 7, 2022, to Address National Security Concerns Posed by PRC Military Modernization

Washington, D.C.--Today, the U.S. Department of Commerce's Bureau of Industry and Security (BIS) released a package of rules designed to update export controls on advanced computing semiconductors and semiconductor manufacturing equipment, as well as items that support supercomputing applications and end-uses, to arms embargoed countries, including the PRC, and to place additional related entities in the PRC on the Entity List.

"Today's updated rules will increase effectiveness of our controls and further shut off pathways to evade our restrictions. These controls maintain our clear focus on military applications and confront the threats to our national security posed by the PRC Government's military-civil fusion strategy," said **Secretary of Commerce Gina M. Raimondo**. "As we implement these restrictions, we will keep working to protect our national security by restricting access to critical technologies, vigilantly enforcing our rules, while minimizing any unintended impact on trade flows."

"Export controls are a powerful national security tool, and the updates released today build on our ongoing assessment of the U.S. national security and foreign policy concerns that the PRC's military-civil fusion and military modernization present," said **Under Secretary of Commerce for Industry and Security Alan F. Estevez**. "BIS will continue to assess the security environment and technology landscape and will not hesitate to act as appropriate."

"The Bureau of Industry and Security will continue to demonstrate global leadership in the regulation of advanced computing and artificial intelligence technologies. These technologies inherently serve as force multipliers for humanitarian good and also for undermining global security and advancing repression," said **Assistant Secretary of Commerce for Export Administration Thea D. Rozman Kendler**. "By imposing stringent license requirements, we ensure that those seeking to obtain powerful advanced chips and chip manufacturing equipment will not use these technologies to undermine U.S. national security. We will continue to hone these controls as technology evolves so that our technology is not used to threaten global peace and security."

Source: US BIS (bis.doc.gov)

Rule 1: Advanced Computing Chips Rule (AC/S IFR)

The effective date for this rule will be November 16, 2023, and the deadline for public comments is 60 days from the date the rule is put on public display.

The AC/S IFR retains the stringent PRC-wide licensing requirements imposed in the October 7, 2022 rule and makes two categories of updates:

- 1) **Adjusting the parameters** that determine whether an advanced computing chip is restricted;
- 2) Imposing new measures to address risks of circumvention of the controls, including an **expansion of controls to additional countries**.

Part 1: Parameter Changes:

Based on public comments, recent technological developments, and analysis of the prior rule's national security impact, the AC/S IFR **removes "interconnect bandwidth"** as a parameter for identifying restricted chips. The rule also:

- **Restricts the export of chips if they exceed either of two parameters:**
 - 1) The pre-existing performance threshold set in the October 7 rule; or
 - 2) A new **"performance density threshold,"** which is designed to pre-empt future workarounds
- **Creates a license exception for shipments of certain lower-performance chips.** Under new License Exception Notified Advanced Computing (NAC), following receipt of notification for exports and re-exports to Macau and destinations identified as subject to a U.S. arms embargo (including China), the US government will determine within 25 days whether the transaction may proceed under the license exception or instead require a license. License Exception NAC may be used for exports, re-exports, and transfers (in-country) to or within other countries without prior notification.

As part of these updates, **an exemption that will permit the export of chips for consumer applications** was also introduced.

Part 2: Circumvention Prevention:

- Establishes a **worldwide licensing requirement** for any company that is **headquartered in Macau or a destination subject to the US arms embargo (including the PRC)**, or whose ultimate parent company is headquartered in those countries, to prevent firms from countries of concern from securing controlled chips through their foreign subsidiaries and branches.
- Creates new red flags and additional due diligence requirement under the US persons controls. This will make it easier for foundries to assess whether foreign parties are attempting to circumvent the controls.
- Imposes **additional license requirements on exports to more than 40 additional countries** that present a heightened risk for diversion to China. This will help address potential transshipment by non-PRC companies purchasing chips for resale to China and provide greater visibility into procurement networks and customers of these chips.
- Improves understanding about transactions by **collecting information on the export of less advanced chips** through the notification process described above for exports and re-exports to Macau and destinations subject to US arms embargo.
- Includes a **request for public comments** on multiple topics, including **infrastructure as a service (IaaS) providers**, additional **compliance guidance that could be provided to foundries receiving chip designs**, the application of controls on deemed exports and deemed re-exports, and defining headquartered companies.

Rule 2: Export Controls on Semiconductor Manufacturing Items Interim Final Rule (SME IFR):

The effective date for this rule is 30 days after public inspection on the Federal Register website (except the Temporary General License), and the deadline for public comments is 60 days from the date that the rule is put on public inspection.

Key changes made to the October 7, 2022 rule include:

- Imposes controls on **additional types of semiconductor manufacturing equipment**.
- Refines and better **focuses the US persons restrictions** while codifying previously existing agency guidance.
- Expanding license requirements for semiconductor manufacturing equipment to apply to **additional countries beyond the PRC and Macau, to 21 other countries for which the US maintains an arms embargo**.

Rule 3: Additions to the Entity List

The effective date for this rule is October 17, 2023.

- BIS is adding to the Entity List **two PRC entities and their subsidiaries (a total of 13 entities)** involved in the development of advanced computing chips that have been found to be engaged in activities contrary to US national security and foreign policy interests. These entities will also be subject to restrictions on foreign-produced items made with US technology.
- **Foundries producing chips for these listed parties will need a BIS license** before the foundries may send such chips to these entities or parties acting on behalf of these entities as a result of applying the “footnote 4” Entity List foreign direct product rule designation.

Figure 2: 13 new entities to be added onto US BIS’s Entity List

English Name	Chinese Name
1 Beijing Biren Technology Development Co., Ltd.	北京壁仞科技开发有限公司
2 Guangzhou Biren Integrated Circuit Co., Ltd.	广州壁仞集成电路有限公司
3 Hangzhou Biren Technology Development Co., Ltd.	杭州壁仞科技开发有限公司
4 Light Cloud (Hangzhou) Technology Co., Ltd.	光线云（杭州）科技有限公司
5 Moore Threads Intelligent Technology (Beijing) Co., Ltd.	摩尔线程智能科技（北京）有限公司
6 Moore Threads Intelligent Technology (Chengdu) Co., Ltd.	摩尔线程智能科技（成都）有限公司
7 Moore Threads Intelligent Technology (Shanghai) Co., Ltd.	摩尔线程智能科技（上海）有限公司
8 Shanghai Biren Information Technology Co., Ltd.	上海壁仞信息科技有限公司
9 Shanghai Biren Integrated Circuit Co., Ltd.	上海壁仞集成电路有限公司
10 Shanghai Biren Intelligent Technology Co., Ltd.	上海壁仞智能科技有限公司
11 Superburning Semiconductor (Nanjing) Co., Ltd.	超燃半导体（南京）有限公司
12 Suzhou Xinyan Holdings Co., Ltd.	上海新之砾企业发展有限公司
13 Zhuhai Biren Integrated Circuit Co., Ltd.	珠海壁仞集成电路有限公司

Source: US BIS, CMBIGM

Figure 3: Moore Threads' announcement

声明

摩尔线程 2023-10-17 21:55 发表于北京



我们关注到美国商务部于当地时间 10月17日将摩尔线程列入“实体清单”的消息，对此我们表示强烈抗议。

摩尔线程作为中国GPU领域的领军企业，专注于研发和设计全功能通用型GPU芯片，致力于打造赋能下一代互联网的元计算平台。

摩尔线程自成立以来，严格遵守相关国家和地区的法律、法规，始终秉持合法、合规的企业文化和管理理念，建立了完善的出口管制合规管理体系和工作流程指引。

目前公司正在与各方积极沟通，对于该事项的影响我们正在评估。

摩尔线程智能科技（北京）有限责任公司
2023年10月17日

Source: Bloomberg, CMBIGM estimates

Figure 4: Biren Technology's announcement

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壁仞科技
2023 年 10 月 17 日

Source: Bloomberg, CMBIGM estimates

Figure 5: Biren Technology's GPUs: BR100 and BR104



GPU Model	Architecture	Performance	Memory	Power
壁仞™ 100	OAM 模组形态	2048 TOPS INT8 1024 TFLOPS BF16 512 TFLOPS TF32+ 256 TFLOPS FP32	512GB/s BLink™ 互连带宽 64GB HBM2E 内存	板级功耗 550W
壁仞™ 104	PCIe 板卡形态	1024 TOPS INT8 512 TFLOPS BF16 256 TFLOPS TF32+ 128 TFLOPS FP32	192GB/s BLink™ 互连带宽 32GB HBM2E 内存	板级功耗 300W

Source: Company data, CMBIGM

Figure 6: Moore Threads' GPUs: MTT S80 and MTT S3000



GPU Model	Architecture	Performance	Memory	Power
MTT S80	摩尔线程 MTT S80 核心	GPU 核心频率: 1100MHz 峰值算力: 14.4 TFLOPS 显存容量: 16GB 显存类型: GDDR6 显存带宽: 288GB/s 显存功耗: 140W (典型)	总功耗: 100W (典型)	尺寸: 150mm x 150mm x 150mm
MTT S3000	摩尔线程 MTT S3000 核心	GPU 核心频率: 1100MHz 峰值算力: 14.4 TFLOPS 显存容量: 16GB 显存类型: GDDR6 显存带宽: 288GB/s 显存功耗: 140W (典型)	总功耗: 100W (典型)	尺寸: 150mm x 150mm x 150mm

Source: Company data, CMBIGM

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